

Thermally Conductive PCM / XK-C25

Introduction

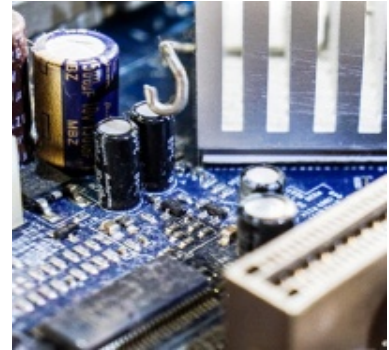
XK-C is produced on the basis of phase-changing properties. Apply to irregular surface between the power module and heat sink, when the application temperature goes above stated temperature, the material will flow and improve the contact between the surfaces and increase the heat transfer.

Features

Special design for easy use and storage
 High viscosity (at 80°) will not drip or run like grease

Applications

High performance computer processors
 Graphic cards



	unit	XK-C25	Method
Reinforcement Carrier			
Filler type		Ceramic	
Color		Gray	visual
Thickness	mm	0.2	ASTM D374
Specific Gravity	g/cm ³	2.9	ASTM D792
Thermal impedance	°Cin ² /W	0.029	ASTM D5470
Thermal Conductivity	W/mK	2.5	HOT DISK
Volume Resistivity	Ωcm	>10 ¹³	ASTM D257
Breakdown Voltage	KV	Non-insulating	ASTM D149
Dielectric Constant	1	NA	ASTM D150
Application temperature	°C	-20~130	
Storage temperature	°C	<23	
Phase change temperature	°C	48	
Siloxane Volatiles D4~D20	%	0	GC-FID